ABSTRACT

An epoxy resin composition for semiconductor encapsulation of the present invention contains an epoxy resin (A) and a curing agent (B) and is used to encapsulate a copper wire (4) and a semiconductor element (1) connected to this copper wire (4). This epoxy resin composition is such that when a cured product of the epoxy resin composition is heated for 10 hours at 200°C, the amount of generation of a first corrosive gas that is a sulfur compound having corrosiveness to the copper wire (4) is less than or equal to 70 ppm.